### 501907366 05/02/2012

## PATENT ASSIGNMENT

# Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

### **CONVEYING PARTY DATA**

Name	Execution Date
Luke D. LaCroix	04/30/2012
Mark Lamorey	04/30/2012
Janak G. Patel	04/24/2012
Peter Slota Jr.	04/30/2012
David B. Stone	04/24/2012

### RECEIVING PARTY DATA

Name:	International Business Machines Corporation
Street Address:	New Orchard Road
City:	Armonk
State/Country:	NEW YORK
Postal Code:	10504

### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13461912

### **CORRESPONDENCE DATA**

Fax Number:(518)220-1857Phone:518-220-1850

Email: kdwileski@iplawusa.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

via US Mail.

Correspondent Name: SCHMEISER, OLSEN & WATTS
Address Line 1: 22 CENTURY HILL DRIVE

Address Line 2: SUITE 302

Address Line 4: LATHAM, NEW YORK 12110

ATTORNEY DOCKET NUMBER:	BUR920110199US1	
NAME OF SUBMITTER:	Anthony M. Palagonia - Reg. No. 41,237	PATENT

501907366 REEL: 028140 FRAME: 0882

00 13461912

# Total Attachments: 6 source=BUR920110199US1-assignment#page1.tif source=BUR920110199US1-assignment#page2.tif source=BUR920110199US1-assignment#page3.tif source=BUR920110199US1-assignment#page4.tif source=BUR920110199US1-assignment#page5.tif source=BUR920110199US1-assignment#page6.tif

### IBM DOCKET NUMBER: BUR920110199US1

### **ASSIGNMENT**

Whereas, the undersigned Inventor(s) has/have made certain inventions, improvements, and discoveries (herein referred to as the "Invention") in:

# Title of the Invention: STRUCTURE AND METHOD FOR MONITORING STRESS INDUCED FAILURES IN INTERLEVEL DIELECTRIC LAYERS OF SOLDER BUMP INTEGRATED CIRCUITS

and further identified by the IBM Docket Number provided above in the header of this Assignment, for which an application for a United States Patent was executed concurrently herewith or was filed having:	
Serial Number:	(insert series code and serial number here if/when available)
business at Armonk, New York (herein refe	Corporation, a corporation of New York having a place of erred to as "IBM"), desires to acquire, and each undersigned worldwide right, title, and interest in and to the Invention and patents directed thereto;

Now, therefore, for good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, each undersigned Inventor ("ASSIGNOR") hereby sells, assigns, and otherwise transfers to IBM (the "ASSIGNEE"), its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefor in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, each undersigned Inventor hereby authorizes and requests the Director of the United States Patent and Trademark Office to issue any United States Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention, to IBM, its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the same to be held and enjoyed by IBM, its successors, legal representatives, and assigns to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made; and each undersigned Inventor agrees to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, in IBM, its successors, legal representatives, and assigns, whenever requested by IBM, its successors, legal representatives, or assigns.

Each undersigned Inventor acknowledges their prior and ongoing obligations to sell, assign, and transfer the rights under this Assignment to IBM and is unaware of any reason why they may not have the full and unencumbered right to sell, assign, and transfer the rights hereby sold, assigned, and transferred, and has not executed, and will not execute, any document or instrument in conflict herewith. Each undersigned Inventor also hereby grants IBM, its successors, legal representatives, and assigns, the right to insert in this Assignment any further identification (including, but not limited to, patent application Serial Number) which may be necessary or desirable for recordation of this Assignment. This Assignment is governed by the substantive laws of the State of New York, and any disputes will be resolved in a New York state court or federal court sited in New York.

Page 1 of 6

Assignment Form final 081908.doc

IBM DOCKET NUMBER: BUR920110199USI

Executed 1	by Inventor 1 of 5	
Signature: Juke Jalin	Date:	4/30/12
(Lulia B. LuCrain)	7000 1 00 00 00 00 00 00 00 00 00 00 00 0	······································

IBM DOCKET NUMBER: BUR920110199US1

Executed by Inventor 2 of 5

usbtvlfp

Page 3 of 6

Assignment Form final 081908.doc

IBM DOCKET NUMBER: BUR920(10199US1

Executed by Inventor 3 of 5

Page 4 of 6

Assignment Form fieal 081908.doc

IBM DOCKET NUMBER: BUR920110199US1

Executed by Inventor 4 of 5

Signature:

usendl2k

Page 5 of 6

Assignment Form final 081908.doc

IDM DOCKET HOMORIN DOKYZHTIGIYYUSI		
Executed by Inventor 5 of 5		
<u> </u>	· / · /· -	

Page 6 of 6

Assignment Form final 081908,doc

**RECORDED: 05/02/2012**